



Title of Change:	Packaging change for TO263 products.	
Effective date:	24 May 2018	
Contact information:	Contact your local ON Semiconductor Sales Office or < Christian.remoreras@onsemi.com >	
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.	
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☒ Other: <u>Packaging</u>	
Change Sub-Category(s):	☐ Manufacturing Site Change/Addition ☐ Manufacturing Process Change ☐ Material Change ☐ Product specific change ☐ Datasheet/Product Doc change ☒ Shipping/Packaging/Marking ☐ Other: _____	
Sites Affected:	ON Semiconductor Sites: ON Cebu, Philippines	External Foundry/Subcon Sites: None

Description and Purpose:

ON Semiconductor, Cebu, Philippines announces the change in packaging for TO263 package in term of the number of empty for the leader and trailer tapes inside the reel.

This is to ensure that additional protection of the units near the reel hub from damage during mishandling of boxes (dropped) which result to lifted leads by increasing the number of empty pockets of the trailer tape.

	Trailer Empty pockets	Leader Empty Pockets
Current	55	70
Proposed Change	90	25

List of Affected Parts:

FDB070AN06A0-F085	FGB3040G2-F085
FDB075N15A-F085	HUF76419S3ST-F085
FDB14AN06LA0-F085	HUFA75639S3ST
FDB2532-F085	HUFA76645S3ST-F085
FDB7030BL	ISL9V2540S3ST
FDB8030L	ISL9V5036S3ST
FDB8442-F085	NDB6020P
FDB86360-F085	NDB6030PL
FDB8880	NDB6060L
FDB9406-F085	

"Please be informed that there may be Customer Specific parts impacted by this Notification, thus MPN & CPN info will not be reflected in the parts list of this Generic document. Instead please click the link to the addendum PCN copy provided in the email notification to see full list of affected products specific to your company."